



7/19/2012

**RELIABILITY MONITOR REPORT
FOR**

X3 TSV Process Flow for stack die (TSV)

MAXIM Integrated Products

120 San Gabriel Dr.
Sunnyvale, CA 94086

**This Report was prepared by
Maxim Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Process Reliability Monitor. The specific products in this process monitor are:

MAX98314EWL

The calculated failure rate for devices using this process is:

FAILURE RATE: MTTF (YRS): 44764 QUANTITY: 231 FAILS: 0 FITS: 2.6

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 Tu: 25 °C

The reliability data follows and in this section is the detailed reliability data by stress. The reliability data section includes the latest data available. This report covers data between 7/1/2011 and 6/30/2012 .

Process Information:

Process Description: X3 TSV Process Flow for stack die (TSV)

OPERATING LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	LOT NO.
HIGH TEMP OP LIFE	1106	MAX98314EWL+T	135C	1000 HRS	77	0	SX8ZEQ002AC
HIGH TEMP OP LIFE	N/A	MAX98314EWL+T	135C	1000 HRS	77	0	SX8ZEQ003AB
HIGH TEMP OP LIFE	N/A	MAX98314EWL+T	135C	1000 HRS	77	0	SX8ZEQ004AD
Total:						0	
FAILURE RATE:	MTTF (YRS): 44764		QUANTITY: 231	FAILS: 0	FITS: 2.6		